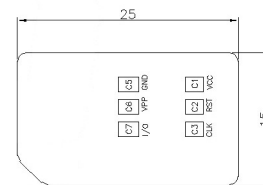
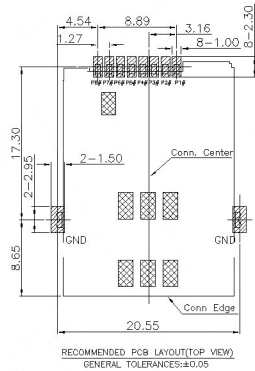
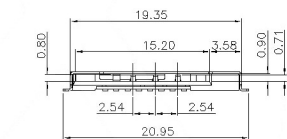
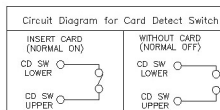
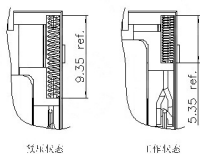


NOTES:

- 1) MATERIAL:
 - HOUSING: LCP UL 94V-0
 - TERMINAL: COPPER ALLOY ,T=0.15
 - SHELL: SUS,T=0.15
 - MYLAR: POLYESTER
- 2) FINISH :
 - TERMINAL:GOLD FLASH PLATED ON CONTACT AREA;
 - GOLD FLASH PLATING ON SOLDER TAILS, WITH ENTIRE CONTACT UNDERPLATED
 - 50u^mMin,NICKEL
 - SHELL: 50u^mMin. NICKEL UNDERPLATED OVERALL , GOLD FLASH PLATED ON SOLDER TAILS
- 3)INFRARED REFLOW SOLDERING: 10sec. Min. at 260[±]3^o



PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET



SOLDER AREA
 NONE CIRCUIT DIAGRAM AREA

2FF SIM CARD

ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	8	COPPER ALLOY	
①	Housing	1	LCP UL 94V-0	BLACK

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES	DSND	DATE	SCALE: N/A	MODEL TYPE:
ΔX					ANGULAR ±5°				SIM CARD CONN
ΔX					L ≤ 4 ±0.2	DWN	DATE	VIEW:	PART NO.:
ΔX					4 < L ≤ 16 ±0.3	CHKD	DATE	UNIT: mm	DWG NO.:
					16 < L ≤ 63 ±0.4	APPD	DATE	SIZE: A4	XKSIM-115
					L > 63 ±0.5				WEIGHT SHEET REVISION
www.bodongkaiguan.net www.ksdkg.com						KOSOD TECHNOLOGY CO., LTD			1.0g 1/1 A0